

SOT1099-1

plastic low profile quad flat package; 256 leads; body 28 x 28 x 1.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	LQFP256
Package type industry code	LQFP256
Package style descriptive code	LQFP (low profile quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	136E31
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	8-4-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	27.9	-	28	28.1	mm
E	package width	27.9	-	28	28.1	mm
A	seated height	1.4	-	1.5	1.6	mm
A ₂	package height	1.35	-	1.4	1.45	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	256	-	



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2. Package outline

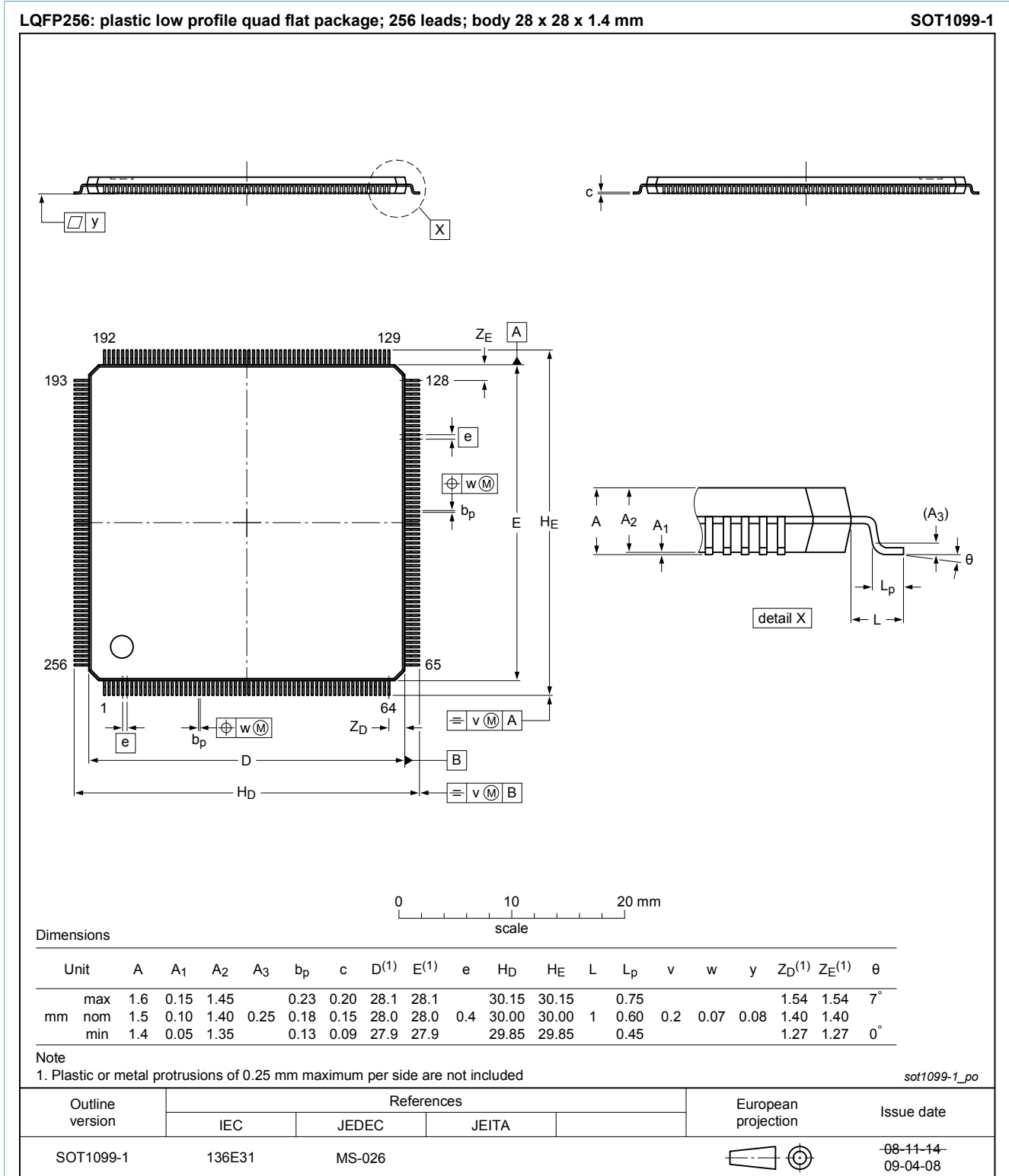


Fig. 1. Package outline LQFP256 (SOT1099-1)

3. Legal information

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